

Amendments to the Specification:

Please replace the paragraph beginning on line 13 of page 20 with the following amended paragraph:

The top mask structure is illustrated in Fig. 24. In this version the entire stack 2401 is deposited on a substrate 2402 coated with a conductor 2403, which may be a transparent conductor 2403. Passivation layer 2404 is applied and a window 2405 is etched to define the active area 2406. The transparent conductive layer 2407 is applied over the window, overlapping the passivation transparent conductive layer 2404. Although there may still be a step for the metal line-out 2408 at the edge of the transparent conductive layer 2407, this is not problematic because it is a conductor-conductor contact and the contact made at the base of the transparent conductive layer 2407 structure will be sufficient.